

Electronics for Physicists

Analog Electronics

Chapter 6; Lecture 11

Frank Simon

Institute for Data Processing and Electronics

23.01.2024

KIT, Winter 2023/24

Chapter 6

2-Transistor Circuits

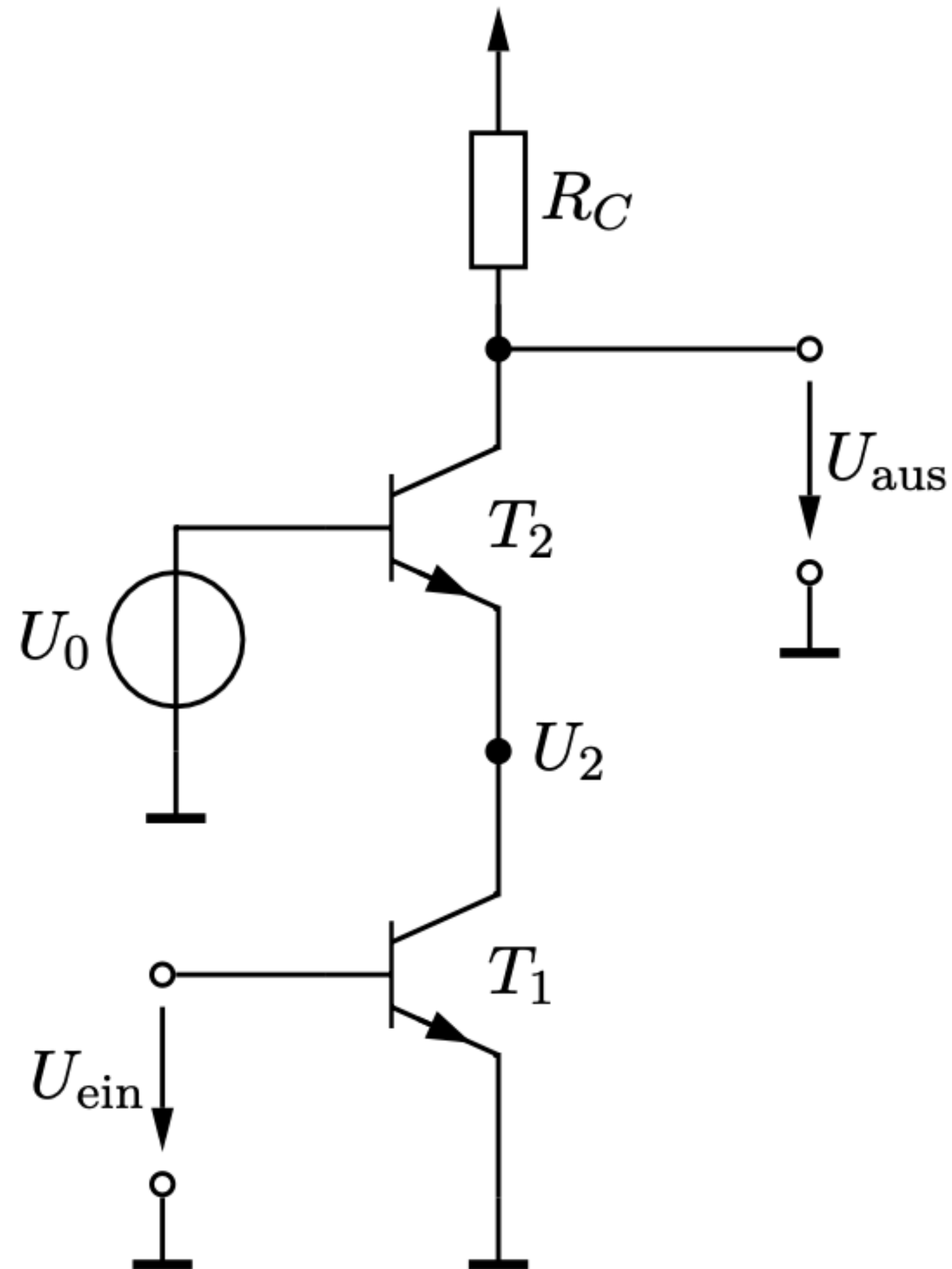
- Current Mirrors
- Amplifier Circuits

Overview

1. Basics
2. Circuits with R, C, L with Alternating Current
3. Diodes
4. Operational Amplifiers
5. Transistors - Basics
- 6. 2-Transistor Circuits**
7. Field Effect Transistors
8. Additional Topics
 - Filters
 - Voltage Regulators
 - Noise

Amplifiers - Part 2

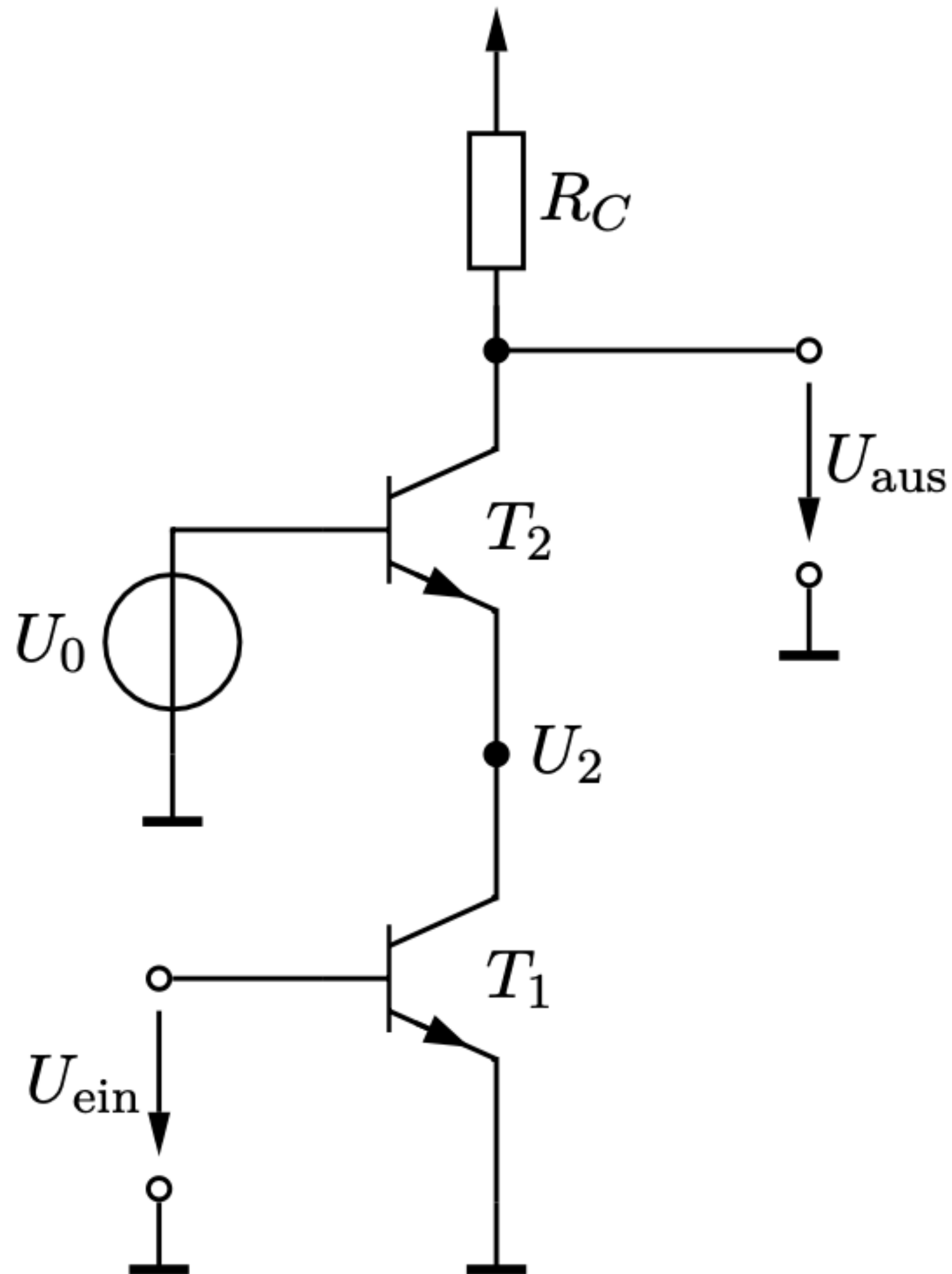
In: Chapter 6: 2-Transistor Circuits



- A very common circuit - cascade of two transistors. Features (compared to a single transistor):
 - Better isolation of input and output, with that: no Miller effect -> higher bandwidth
 - Higher input impedance
 - Also: higher output impedance

The circuit setup:

- Common emitter with T_1
- Common base with T_2 between T_1 and the collector resistor R_C



- How the circuit works
- T_2 as common base amplifier with constant base potential ensures: U_2 relatively constant: U_{E2} , U_{C1}

⇒ Almost no voltage amplification in T_1 :
 $dU_2 \sim dU_{\text{ein}}$

Additional consequence: no Miller effect due to C_{BC1} !

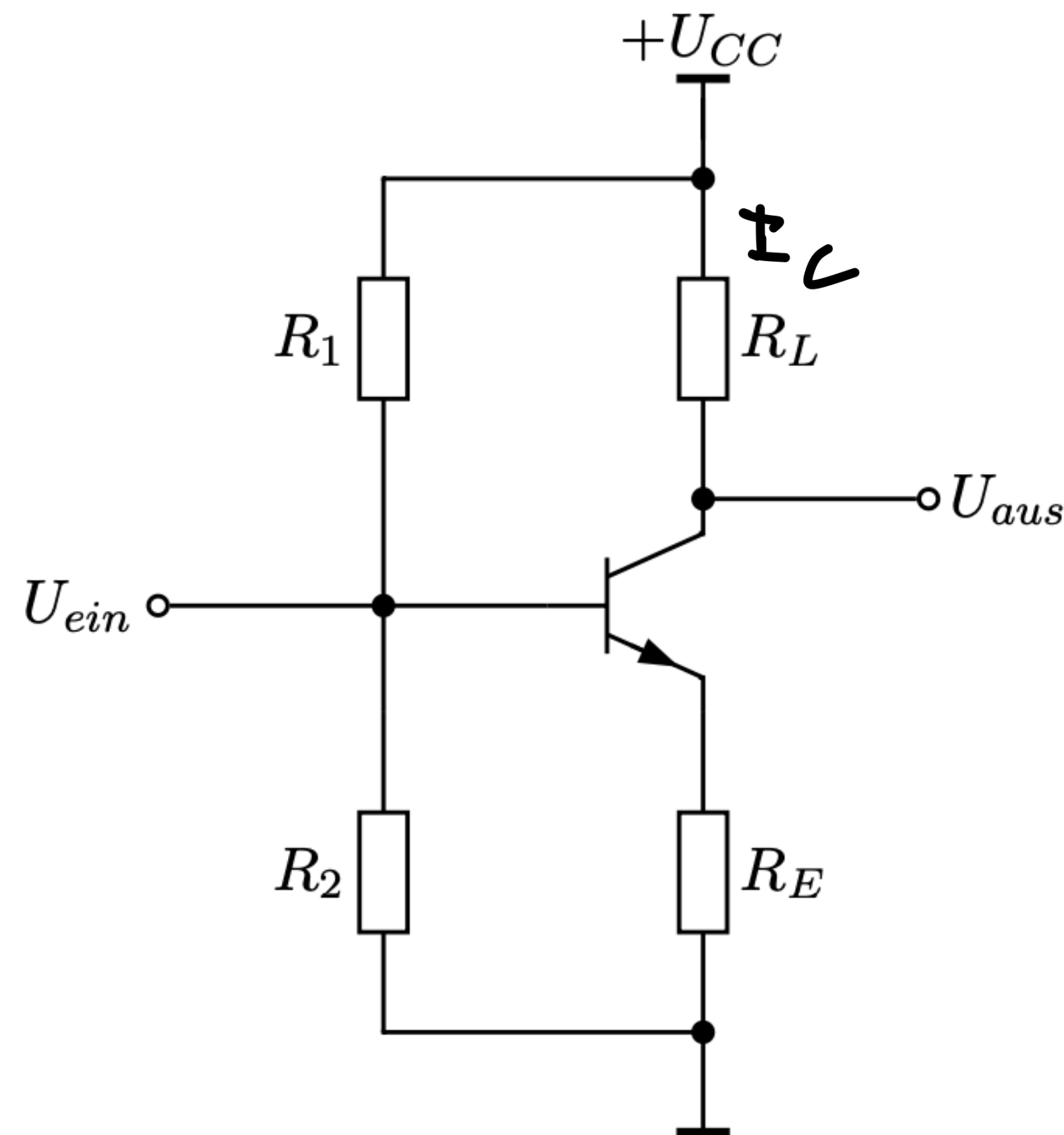
How does this provide voltage gain?

Via T_2 :

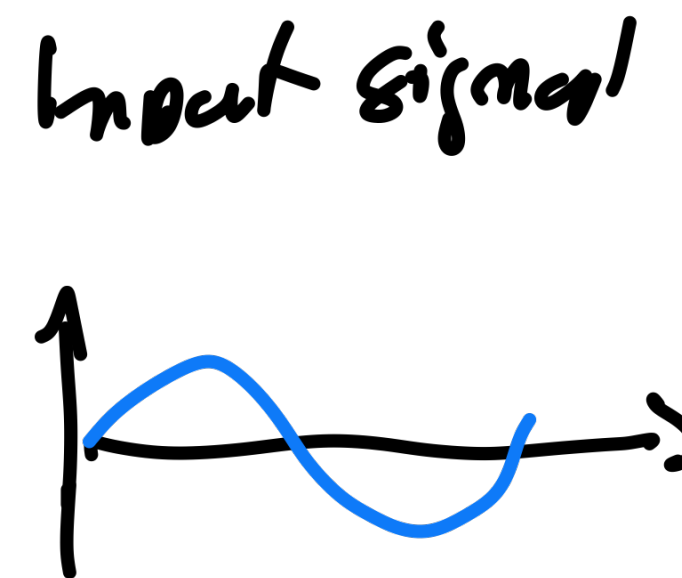
$$V_U = \frac{dU_{\text{aus}}}{dU_{\text{ein}}} \approx \frac{dU_{\text{aus}}}{dU_{U_2}} = SR_C \quad \text{see Ch. 5}$$

- Amplifiers are grouped into classes depending on working principle - most common: A, B, AB

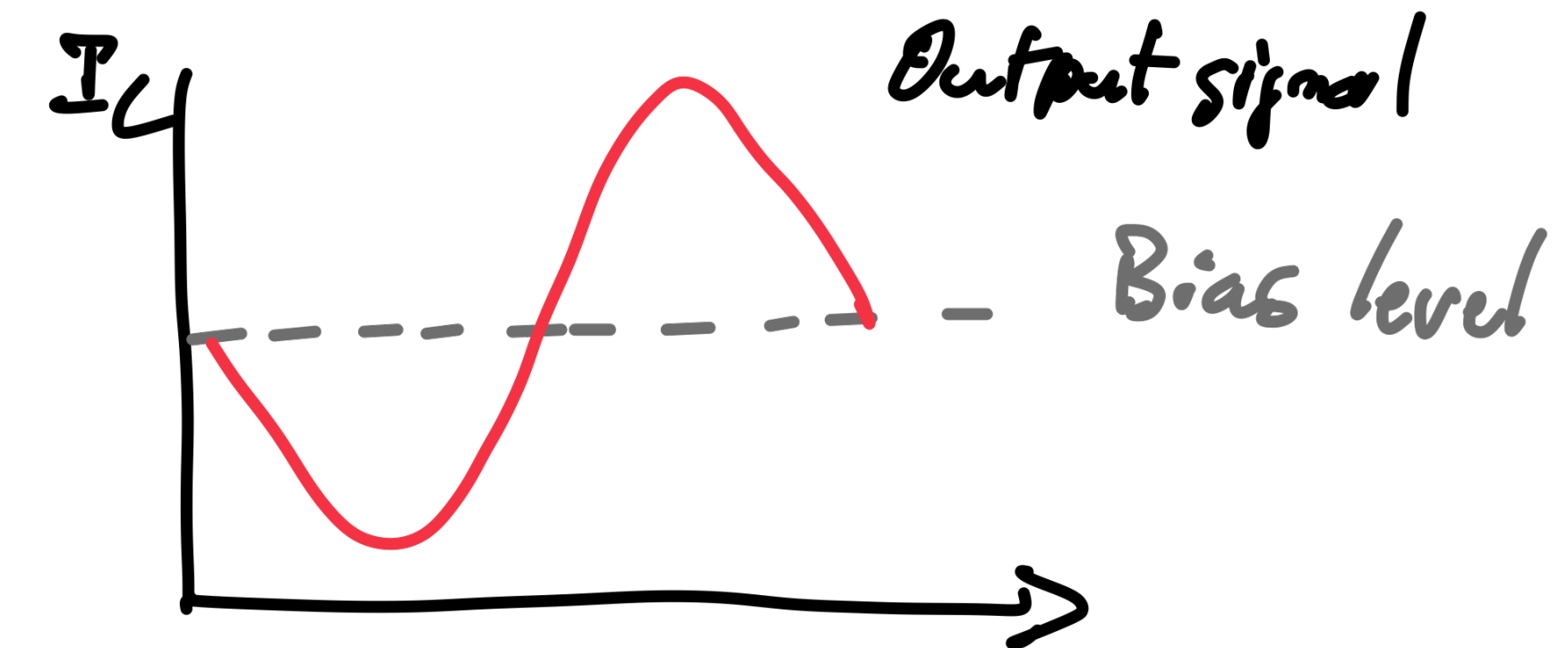
Class A



Working point adjusted such that the full signal is amplified:
positive and negative half-wave



\Rightarrow

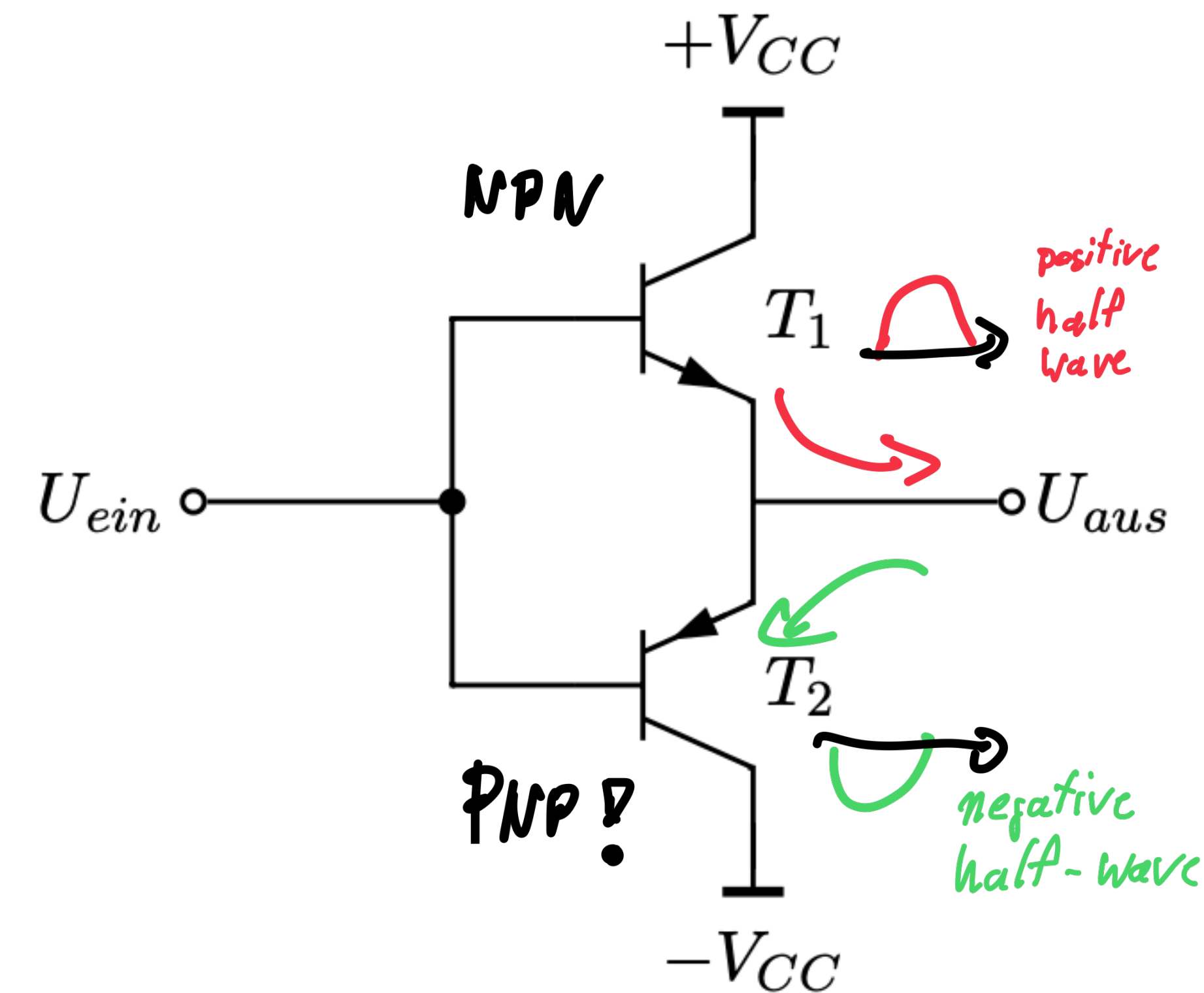


The Pro: Distortion-free amplification of the full signal.

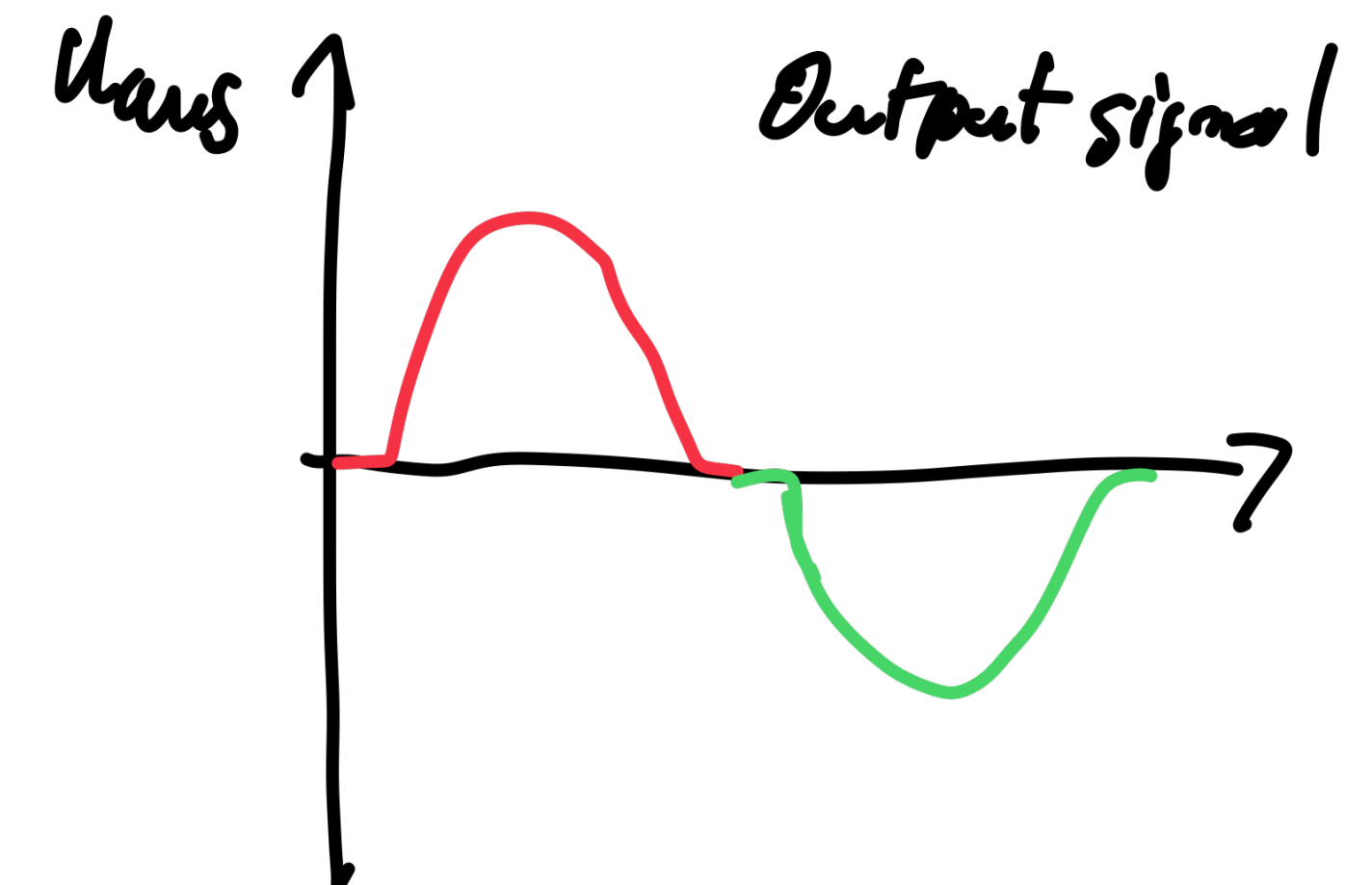
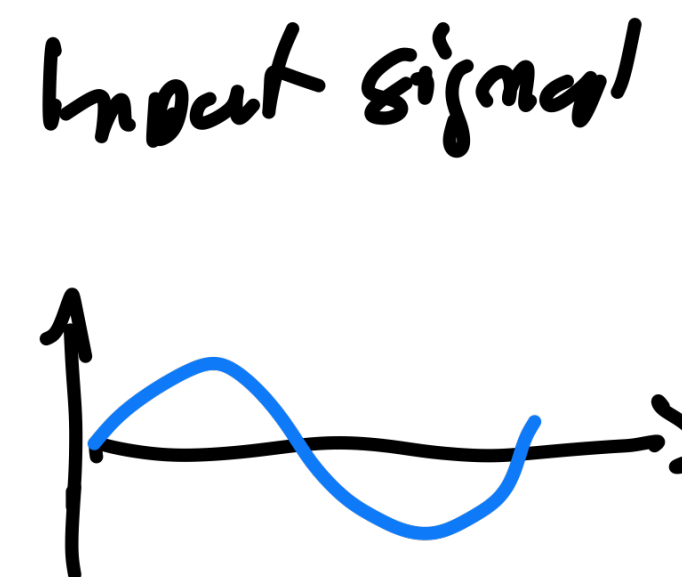
The Con: Low efficiency: Large power also without signal.

- Amplifiers are grouped into classes depending on working principle - most common: A, B, AB

Class B



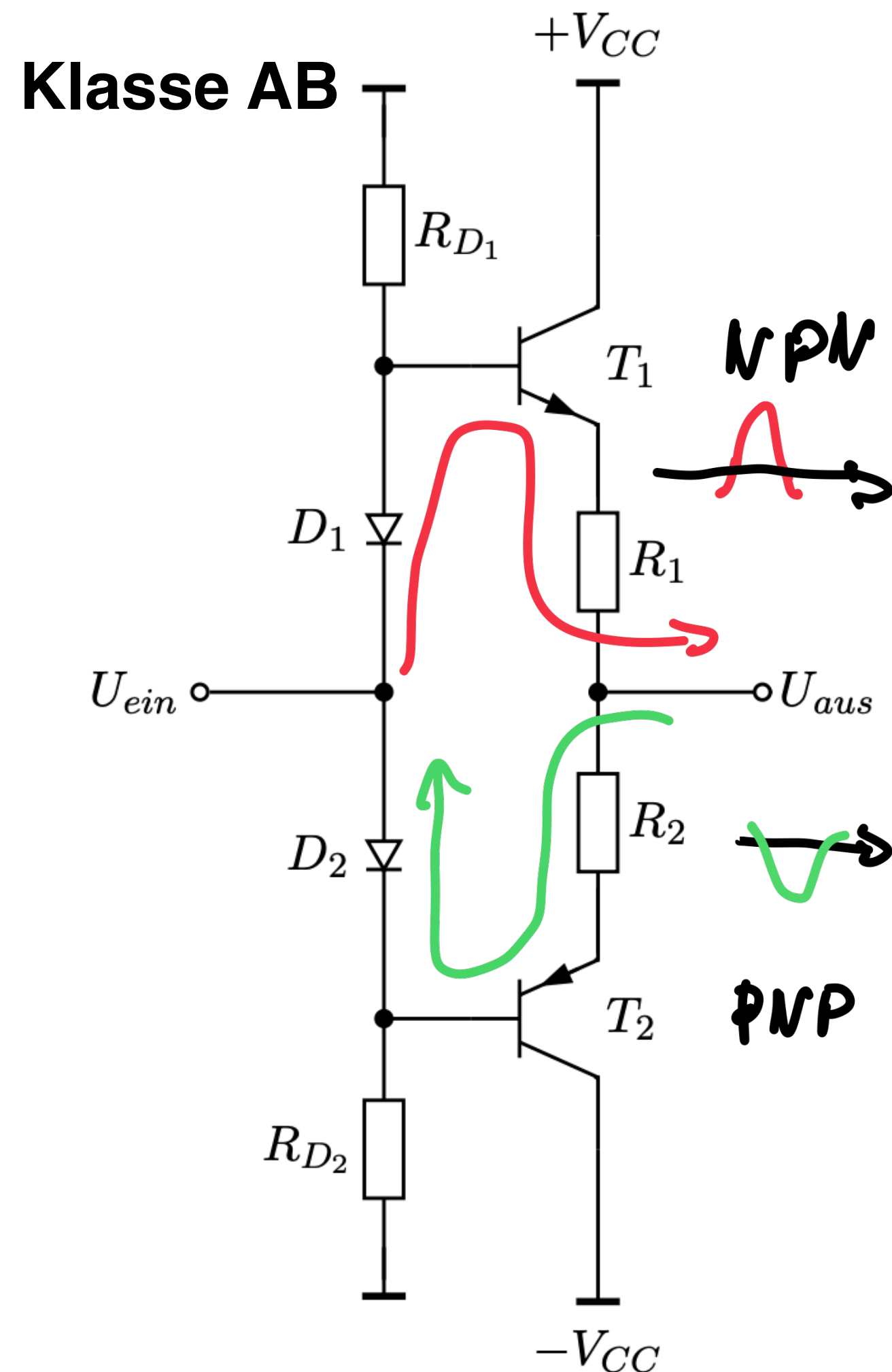
Combination of NPN and PNP transistor - "push-pull amplifier"



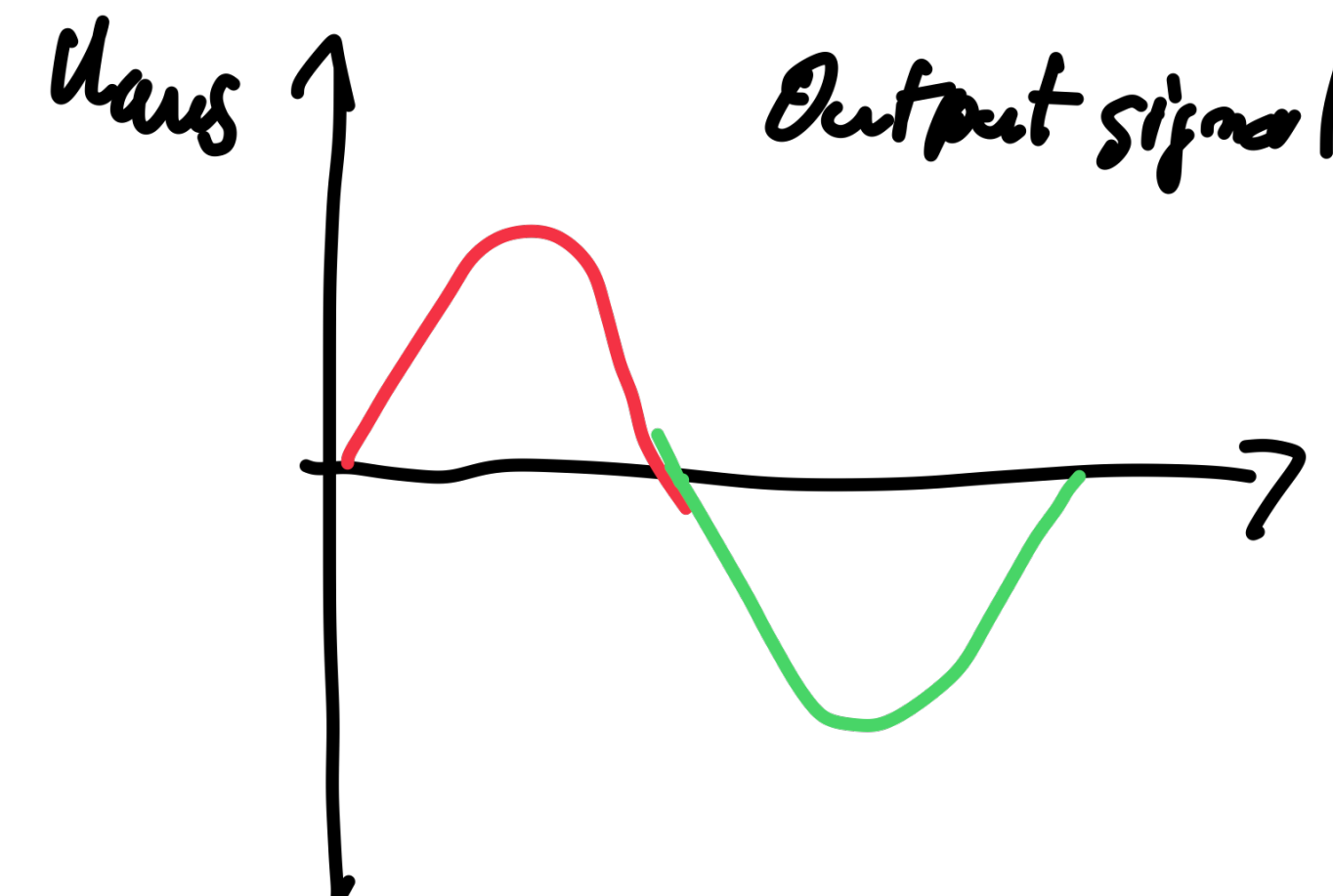
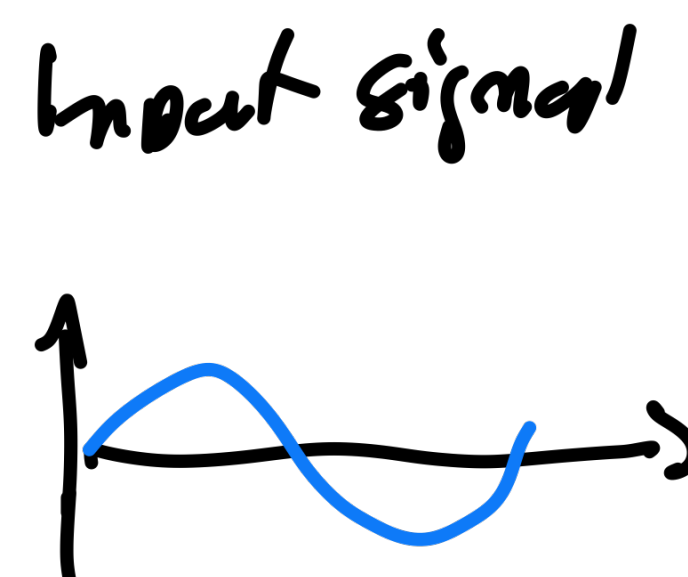
The pros: High energy efficiency - no power w/o signal

The cons: Amplification only for signals $|U_{ein}| > 0.7 \text{ V}$: Distortion when passing through 0 V, also due to switching between transistors.

- Amplifiers are grouped into classes depending on working principle - most common: A, B, AB



Extension of class B amplifier by adding offset voltages to prevent distortions.

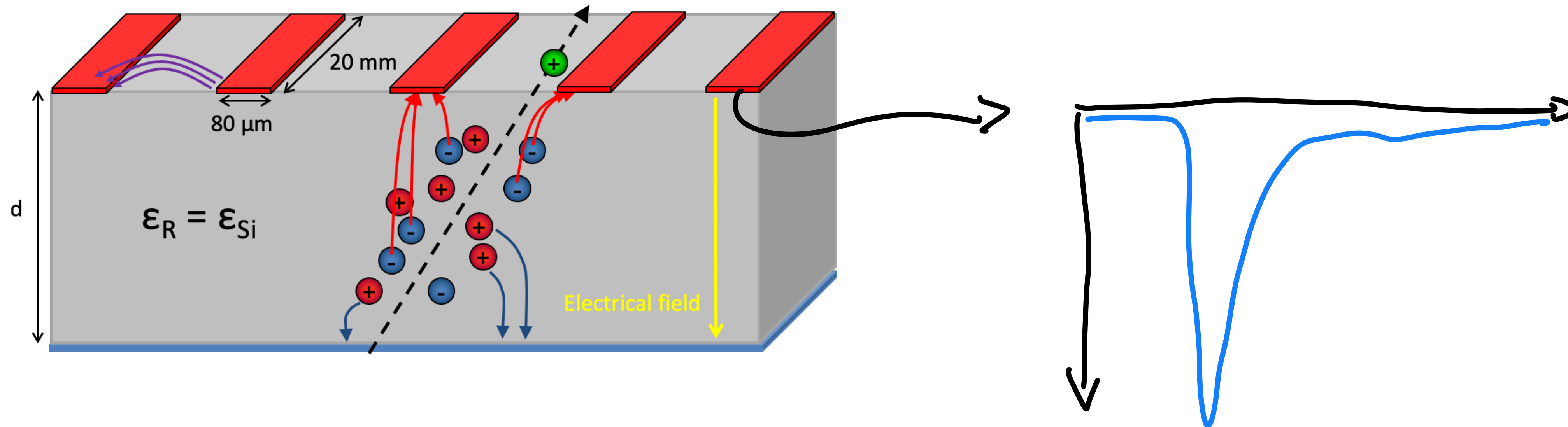


The pros: Good energy efficiency - only small base power, still or only small (or no) distortions.

The cons: More complicated than class A (but still small distortions), more power than class B.

Often: The best compromise, for example for audio amplifiers

- Class A well suited for unipolar signals: Working point adjusted such that also small signals are amplified,, but still no (large) current flows w/o signal.



Detector signals normally are unipolar: Class A often suitable.

Different situation: audio signals etc.: Class A for highest quality, but high power.
Class AB or B depending on willingness for compromises.

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Chapter 7; Lecture 11 - Part 2

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Chapter 7

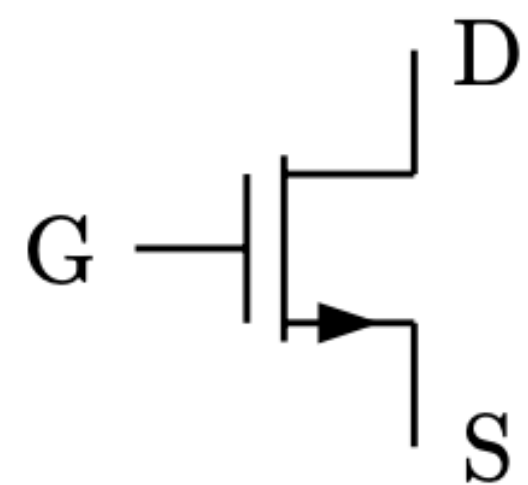
Field Effect Transistors

- MOSFET Basics
- Excursion: CMOS Technology
- CMOS Circuits

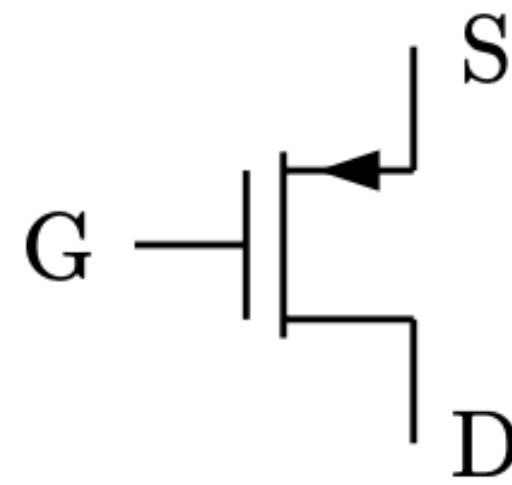
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- Two basic types:
 - Metal Oxide Semiconductor Field Effect Transistor (MOSFET)
 - Junction Field Effect Transistor (JFET)

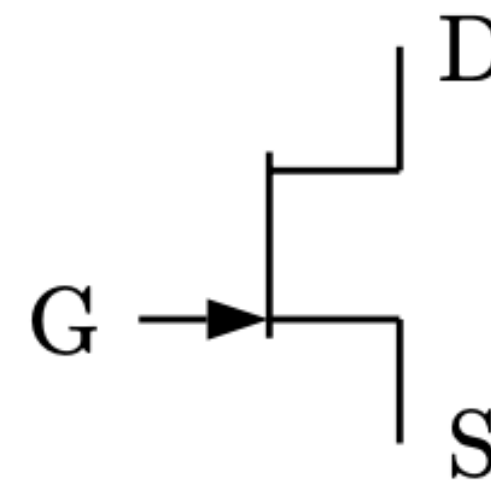


NMOS

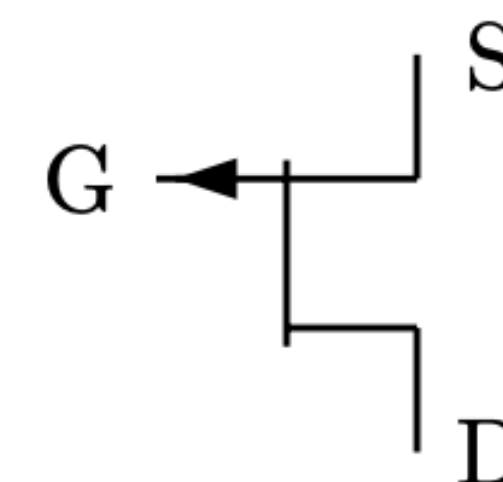


PMOS

MOSFET



n-Kanal



p-Kanal

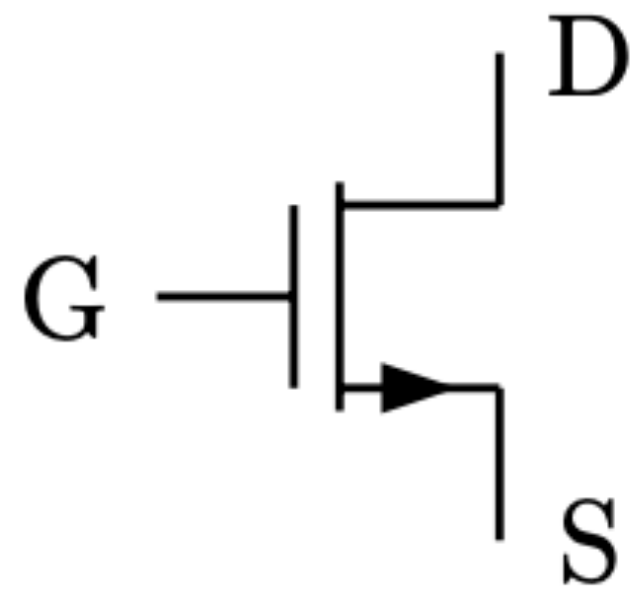
JFET

Gate
Source
Drain

MOSFETs are the most common transistors -> Our focus here!

MOSFET Basics

In: Chapter 7: Field Effect Transistors

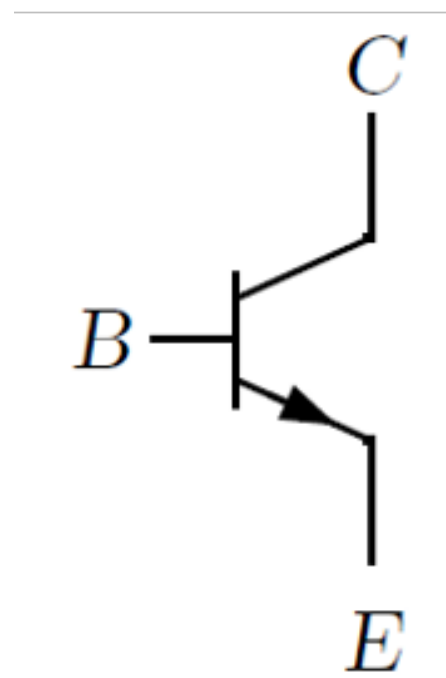


The voltage at the gate U_{GS} defines the current flow between drain and source

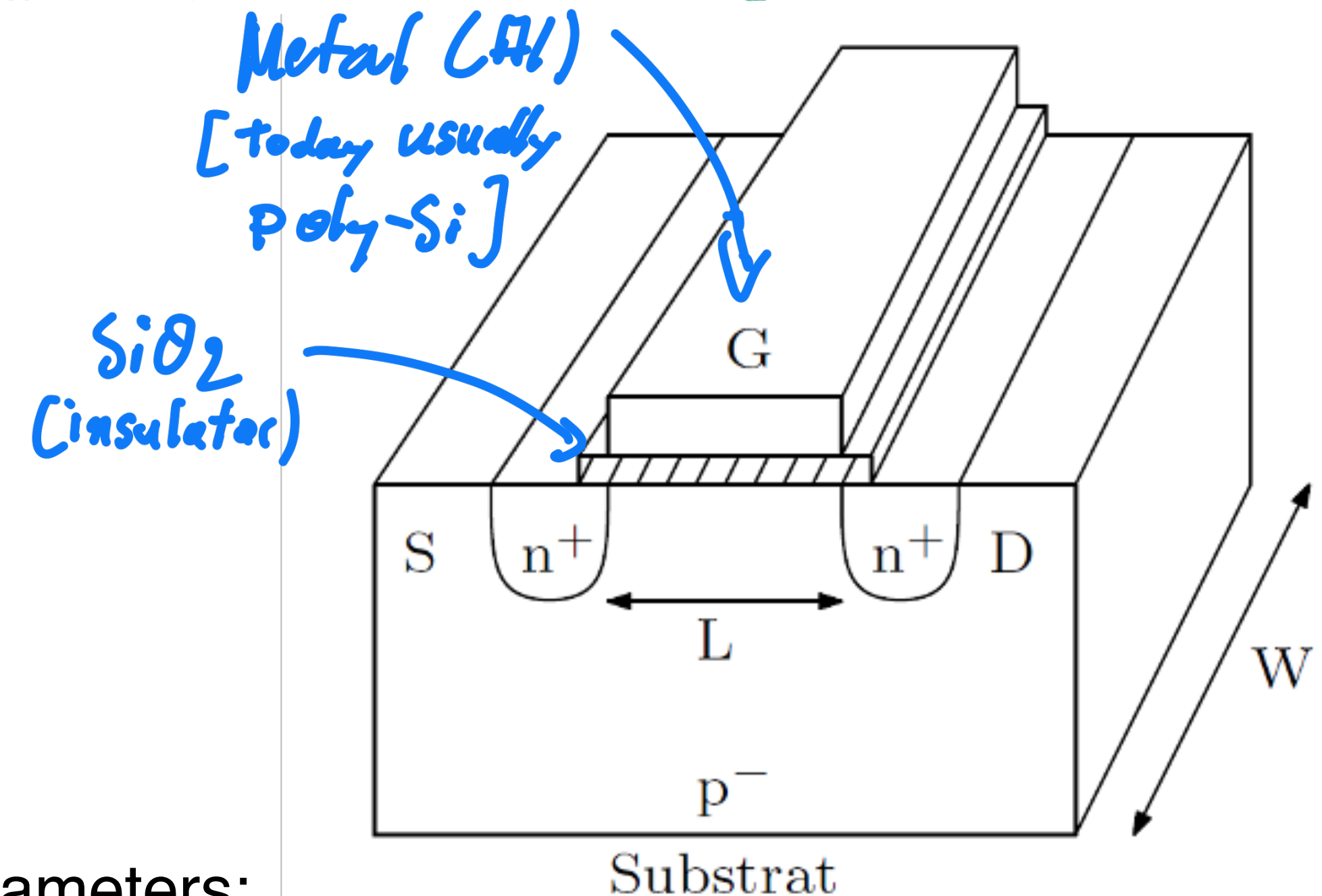
⇒ Voltage-driven current source

No current flow from G to S (with AC input there is a gate current due to charging / discharging of the gate capacity)

Significantly different from BJT:

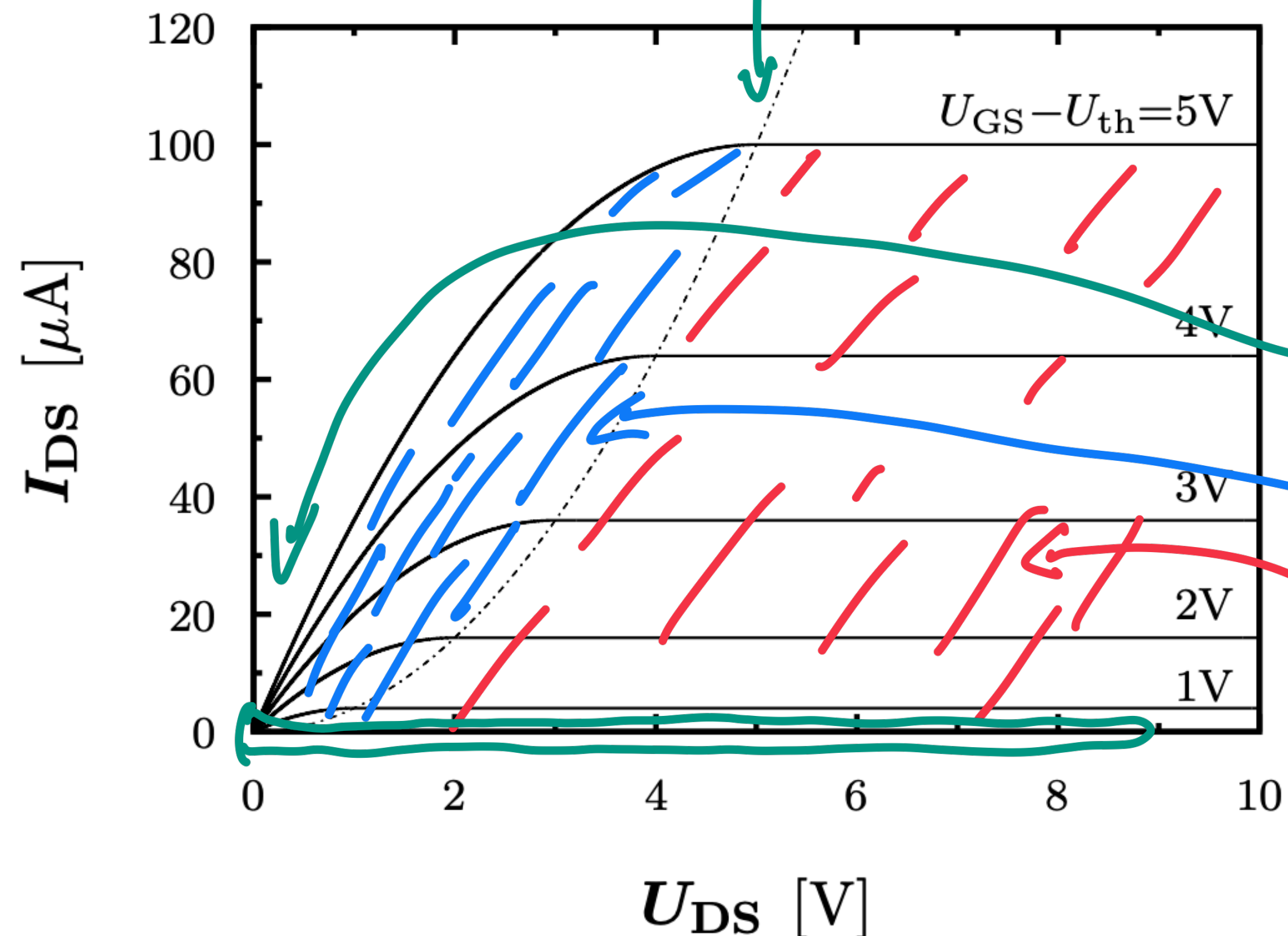


Current-driven current source,
current from base to emitter



- Parameters:
- Substrate thickness: typ. $\sim 700 \mu\text{m}$
- Gate length L : Defined by technology - for example 22 nm, or 250 nm
- Gate thickness: Defined by technology gegeben - zB 1 nm or 5 nm
- Width W : Choice of the designer, but $W \geq L$

Transition from linear - saturation
($U_{DS} = U_{GS} - U_{th}$)



U_{th} : Transistor-dependent threshold voltage
(a few 100 mV)

- Drain-source current I_{DS} as function of U_{DS} for different gate voltages U_{GS}
- Requires $U_{DS} > 0$ and $U_{GS} > U_{th}$ for current flow.

NMOS - Transistor

Distinguishing three different regions

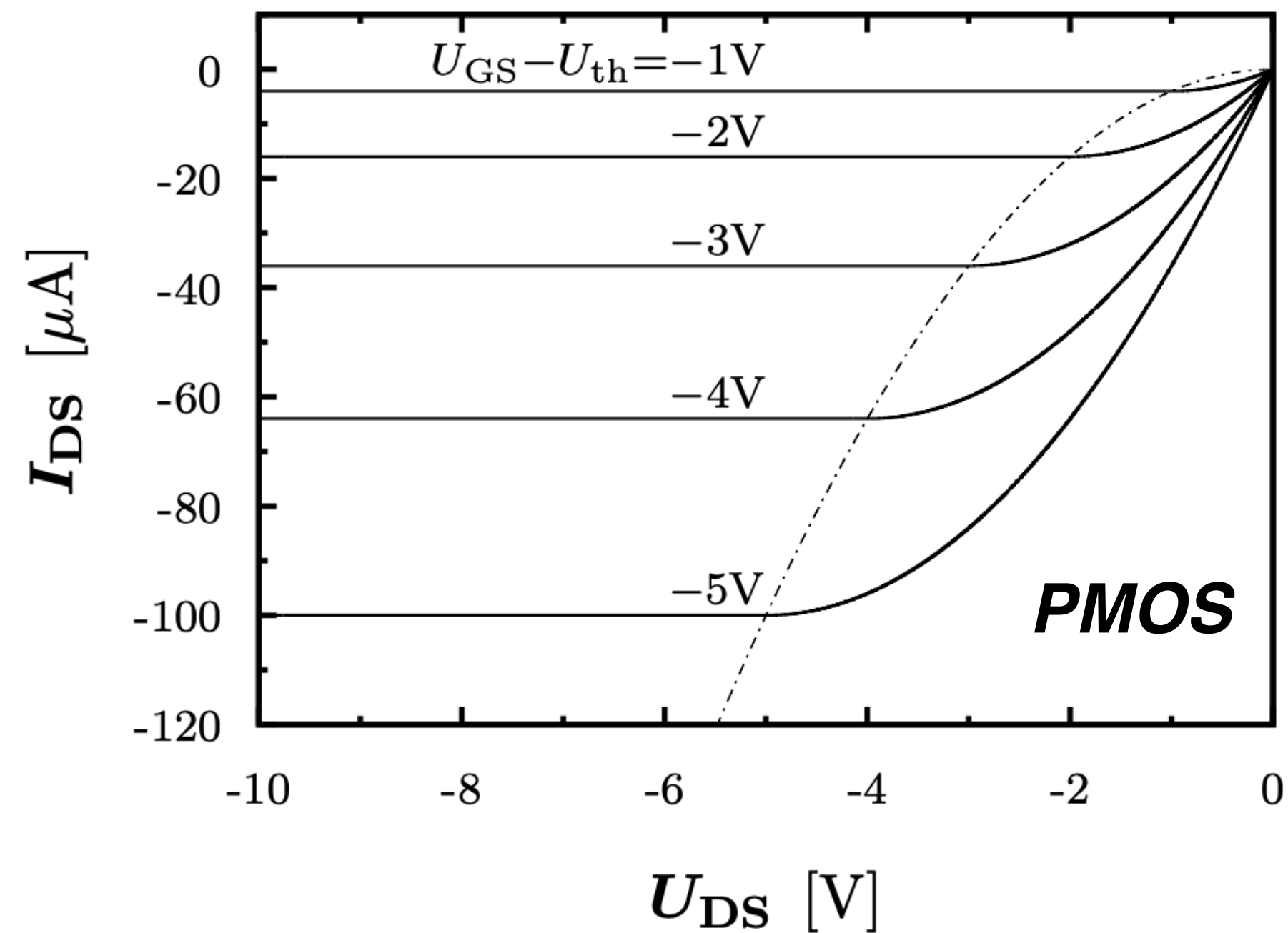
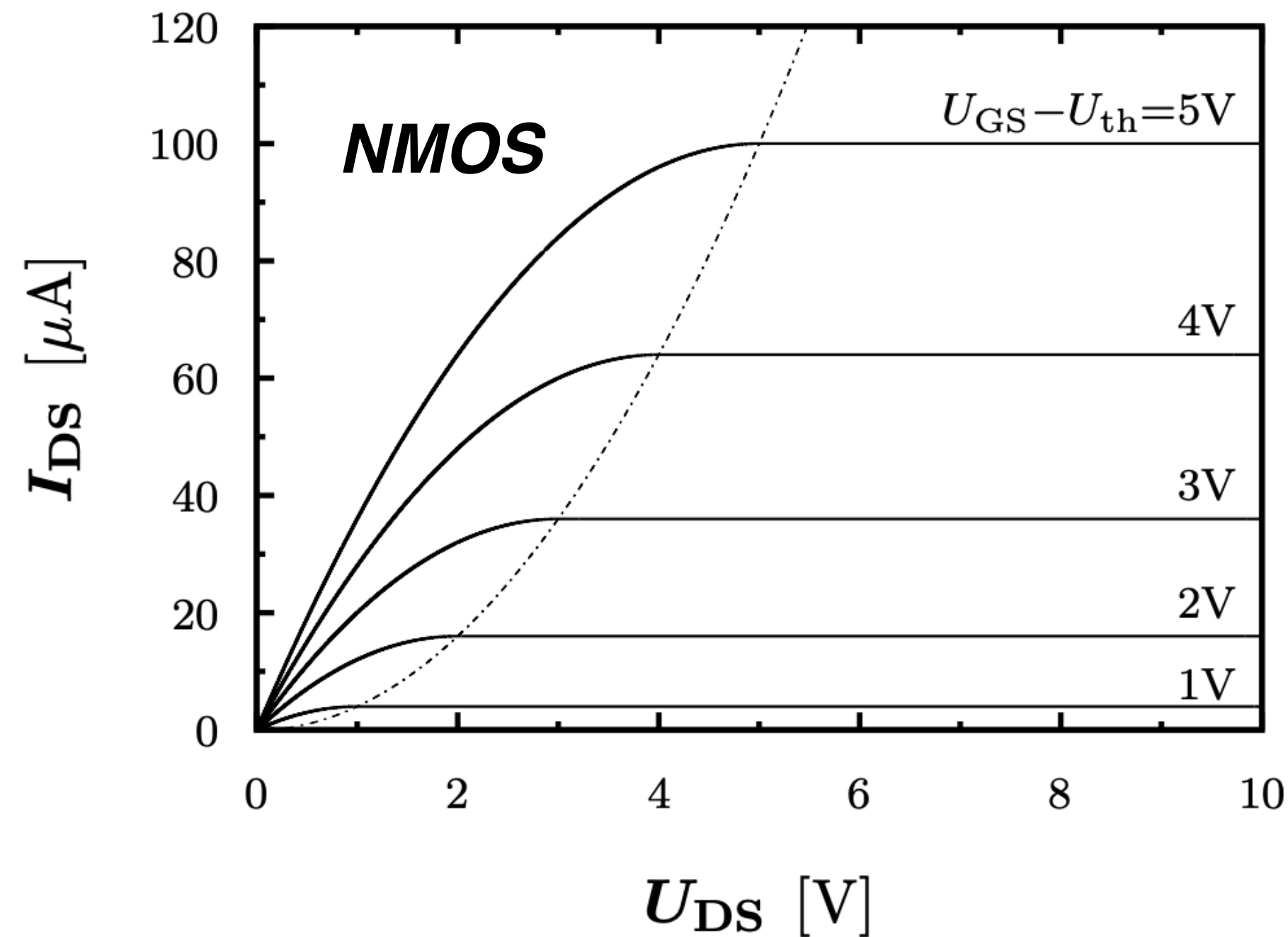
- „Cut-off“ or „weak inversion“ ($U_{GS} < U_{Th}$)
- Linear or ohmic region
- „Strong inversion“ or saturation region

NB: The nomenclature is a bit confusing: For MOSFETs the saturation region corresponds to large U_{DS} , for BJTs it is small U_{CE}

FET IV Curves

NMOS and PMOS

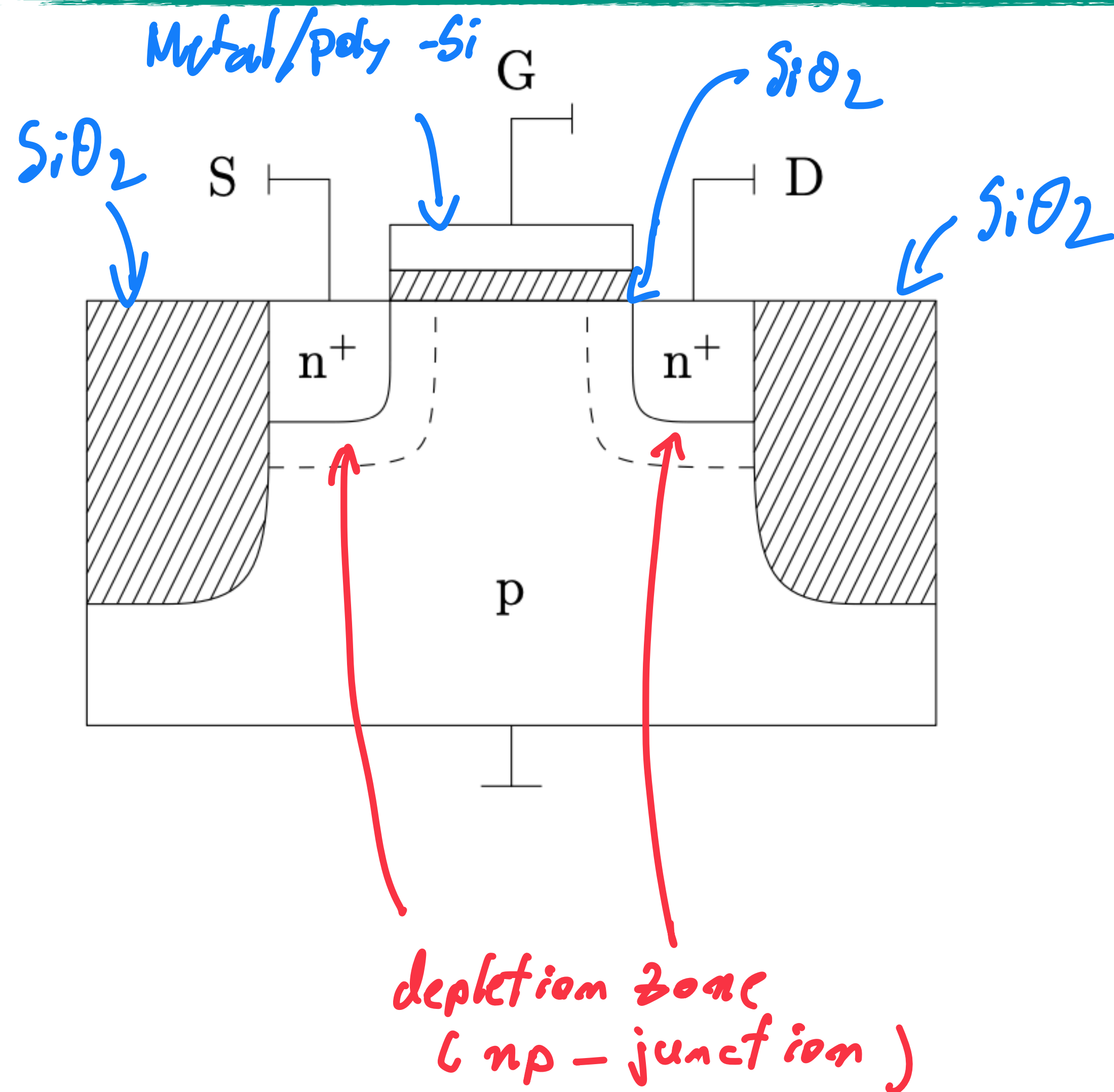
- Drain-Source current I_{DS} as a function of U_{DS} for different gate voltages U_{GS}



Just as for the BJT transconductance is defined as: $g_m = \frac{dI_{DS}}{dU_{GS}}$ *Steilheit*

FET Operating Principle - NMOS

Cut-off / Weak Inversion



- Cut-off (*Sperr-Bereich, Unterschwellenbereich*):

$$U_{GS} < U_{th}$$

leakage current (sub-threshold current)
due to thermal excitation:

$$I_{DS} = I_{DS_0} e^{\frac{U_{GS} - U_{Th}}{n U_T}} \quad \text{as for diodes: } n > 1$$

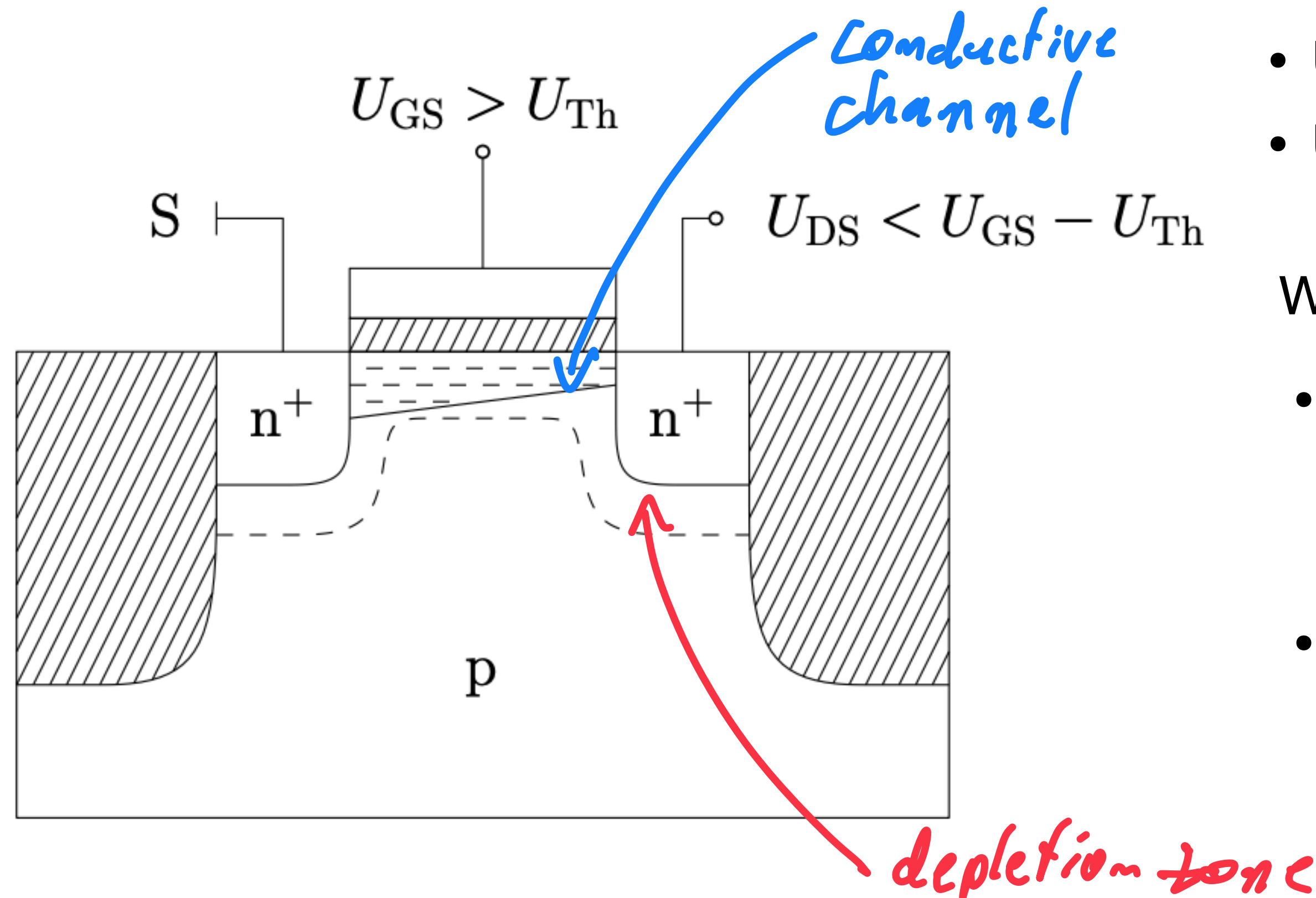
$$I_{DS_0} = I_{DS}(U_{GS} = U_{Th})$$

$$\text{Transconductance: } g_m = I_{DS} \frac{q_e}{n k_B T}$$

In general: a rare operating mode - for example
for applications with extremely low power.

FET Operating Principle - NMOS

Linear / Ohmic Region



- $U_{GS} > U_{Th}$: transistor switched “conductive”
- $U_{DS} < U_{GS} - U_{Th}$

What is happening:

- Conductive channel under gate with free neg. charge carriers: Inversion charge (holes are pushed out)
- U_{GS} determines the available charge
- Voltage between source and drain U_{DS} results in current flow via free charge carriers in channel

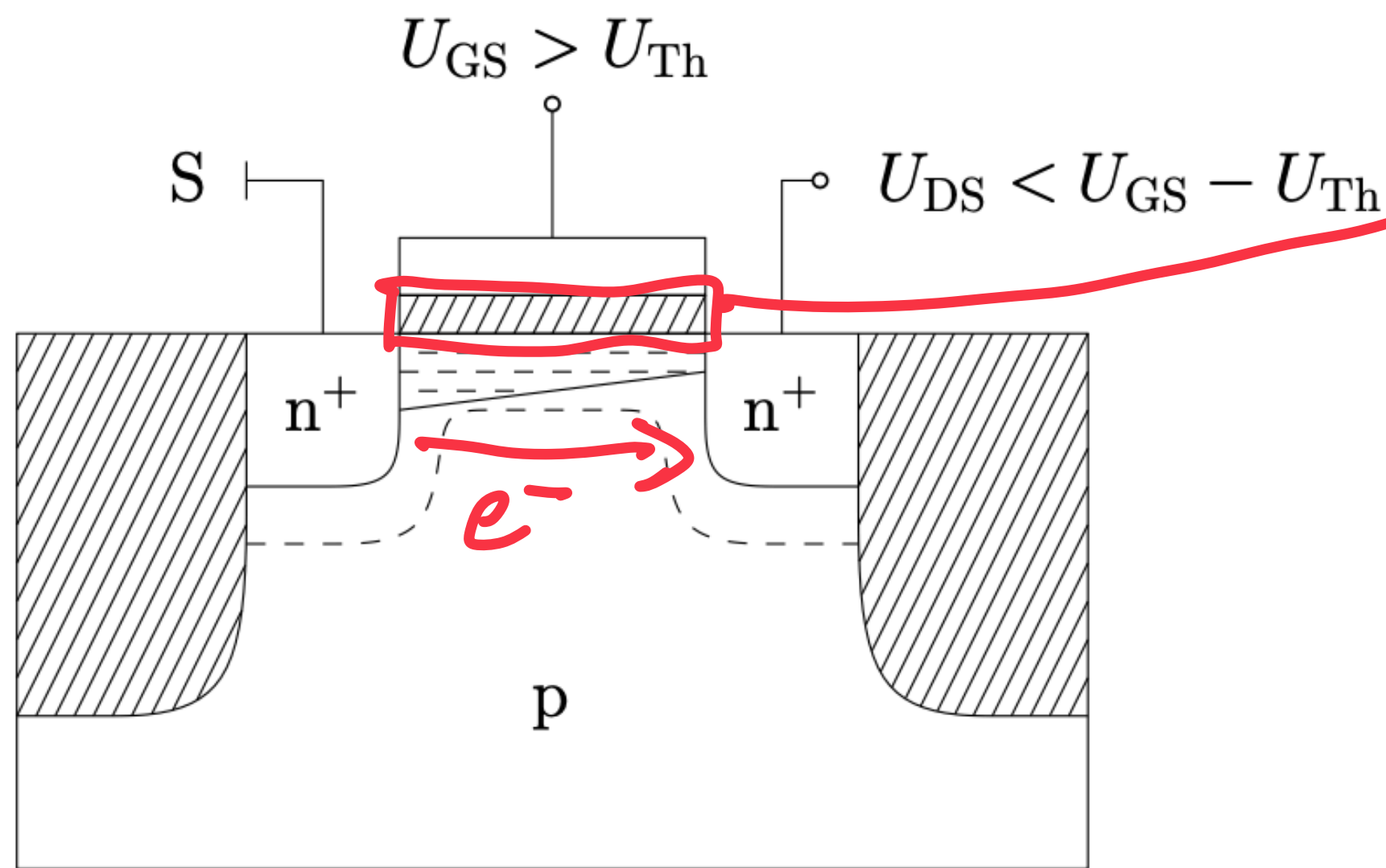
Current between drain and source:

$$I_{DS} = \beta \left[U_{GS} - U_{Th} - \frac{U_{DS}}{2} \right] U_{DS}$$

- ⇒ Behaves as a ohmic resistor controlled via U_{GS} .
(NB: β not the same as for BJT)

FET Operating Principle - NMOS

Linear Region - Derivation



Understanding the working principle:

Considering the gate as a capacitor:

$$\text{Surface charge: } Q_F = C_{Ox} \cdot (U_{GS} - U_{Th}) \quad (\text{for } U_{DS} = 0)$$

$$\text{with } C_{Ox} = \epsilon_0 \epsilon_{SiO_2} \frac{1}{d_{Ox}} \quad (\epsilon_{SiO_2} \sim 11.9)$$

$$\text{For } U_{DS} > 0: \quad Q_F = C_{Ox} \cdot (U_{GS} - U_{Th} - U(x))$$

(U(x) Voltage between source and position x in channel)

Current between source and drain due to free charges, which are drifting in the field created by the voltage:

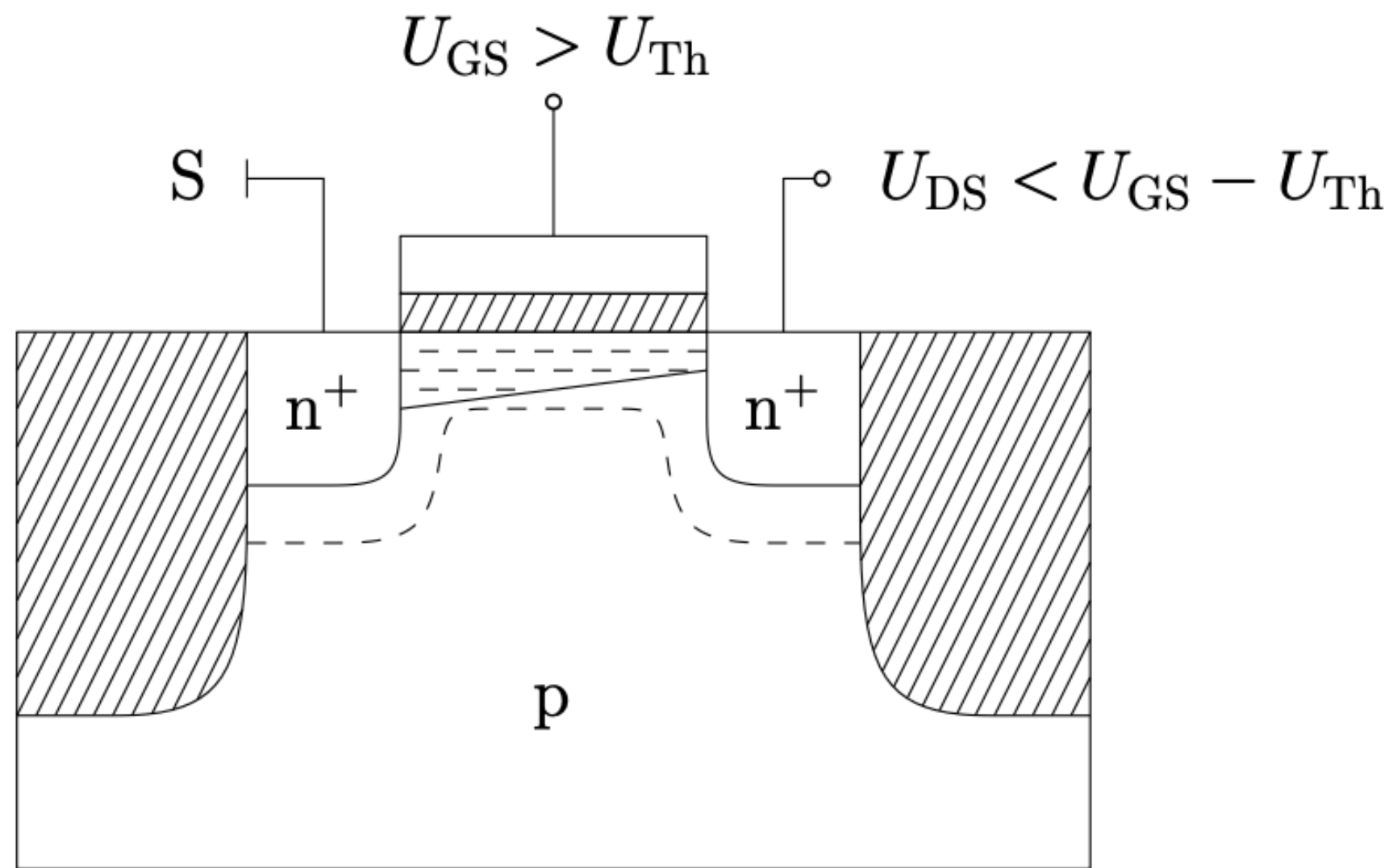
given by mobility of the charge carriers μ :

$$v_D = \frac{dx}{dt} = \mu E_{Drift} = \mu \frac{U_{DS}}{L} \quad , \text{ also: } v_D = \mu \frac{dU(x)}{dx}$$

In Si: holes $\sim 450 \text{ cm}^2/\text{Vs}$, electrons $\sim 1400 \text{ cm}^2/\text{Vs}$

FET Operating Principle - NMOS

Linear Region - Derivation



Understanding the working principle - Part II:

Current via moving charge:

$$I_{DS} = \frac{dQ}{dt} = Q_F W \frac{dx}{dt} \quad (W: \text{width of the channel / gate})$$

$$\Rightarrow I_{DS} = C_{Ox} W (U_{GS} - U_{Th} - U(x)) \mu \frac{dU(x)}{dx}$$

Integration over the full length of channel / gates (= from 0 to U_{DS}):

$$\begin{aligned} I_{DS} \int_0^L dx = I_{DS} L &= \mu C_{Ox} W \int_0^{U_{DS}} (U_{GS} - U_{Th} - U(x)) dU = \\ &= \mu C_{Ox} W (U_{GS} - U_{Th}) U_{DS} - \frac{U_{DS}^2}{2} \end{aligned}$$

Results in:

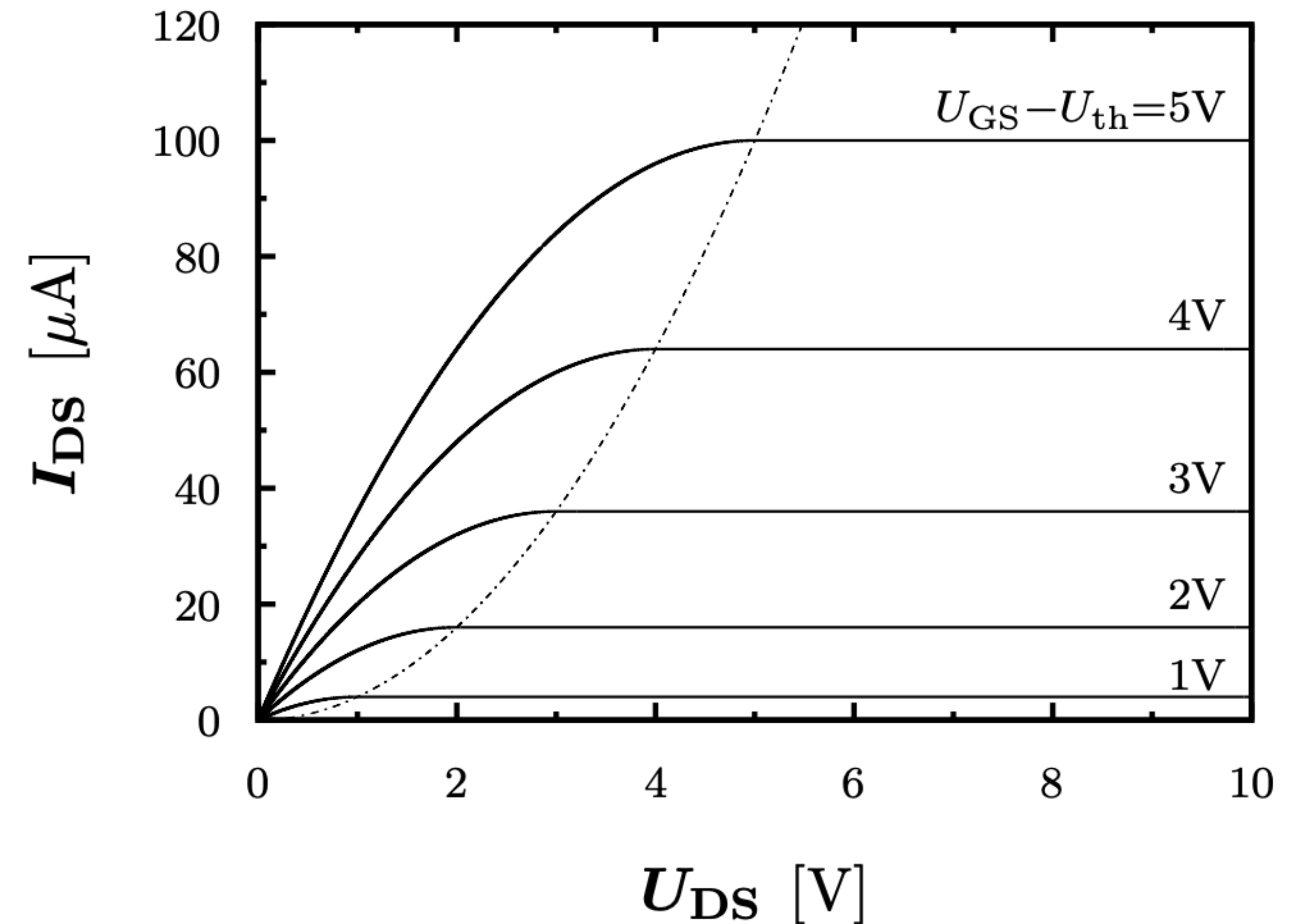
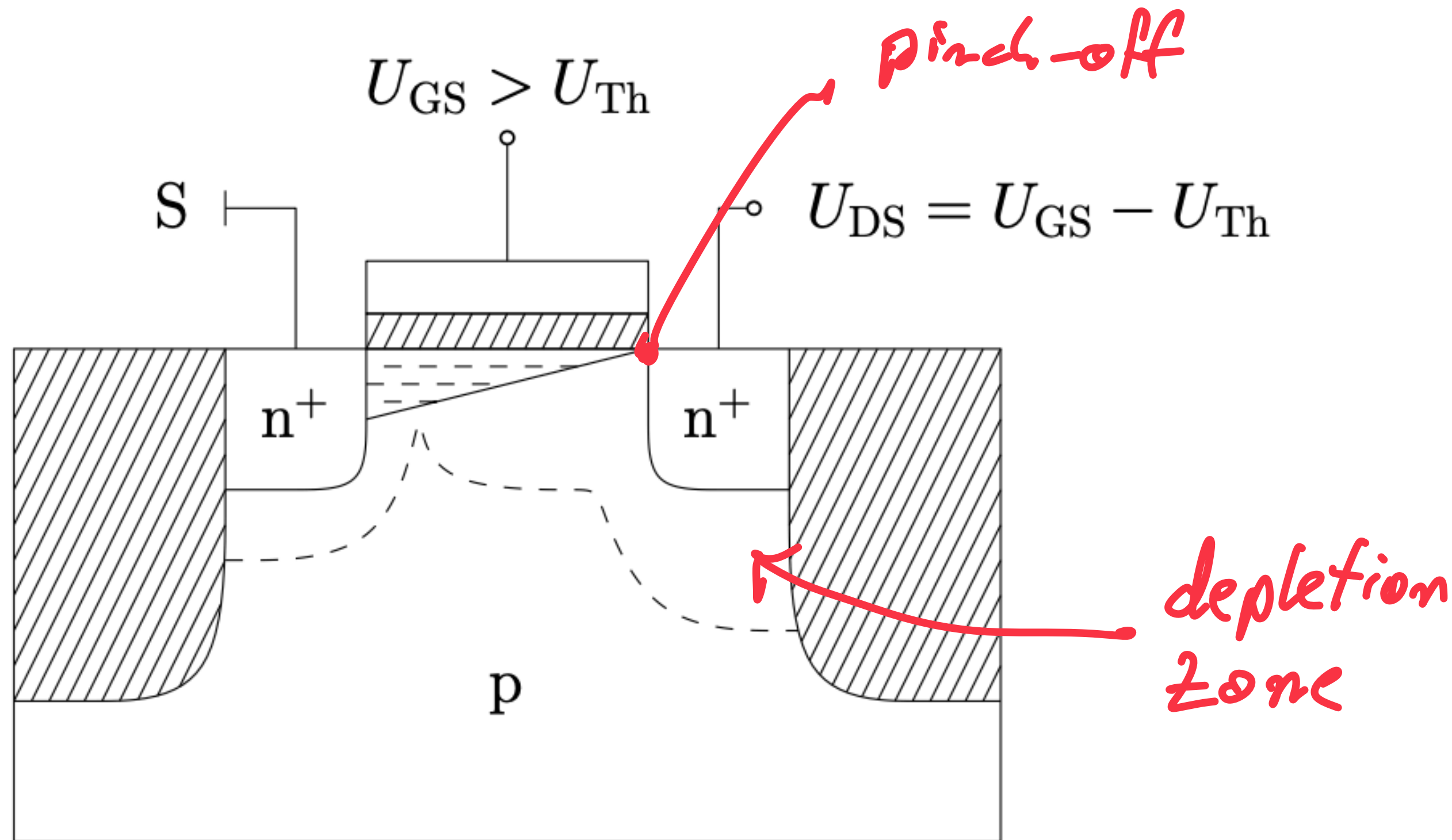
$$I_{DS} = \mu C_{Ox} \frac{W}{L} (U_{GS} - U_{Th}) U_{DS} - \frac{U_{DS}^2}{2}$$

$$I_{DS} = \beta \left(U_{GS} - U_{Th} - \frac{U_{DS}}{2} \right) U_{DS}$$

Defines transconductance coefficient $\beta = \mu C_{Ox} \frac{W}{L}$

FET Operating Principle - NMOS

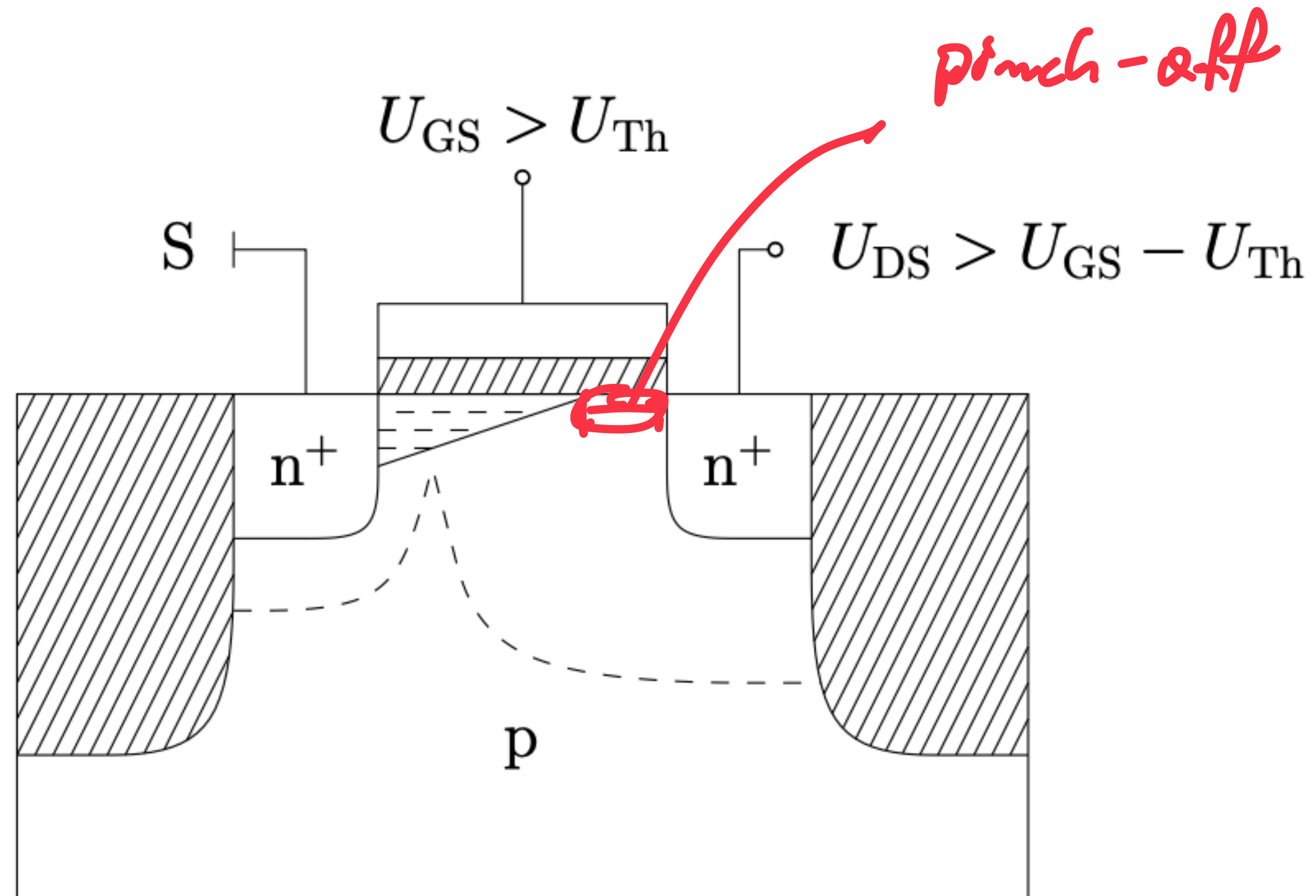
Strong Inversion



- Pinch-off of the channel on the drain side (“abschnüren”)

FET Operating Principle - NMOS

Strong Inversion



- With increasing voltage U_{DS} :
Stronger pinch-off, resulting in reduced surface area in channel and reduced number of charge carriers, simultaneous increase of voltage: no further increase in current => **saturation**
- Conduction through depletion zone: Electrons from the channel are “drained” into the drain

Behavior now defined by the saturation voltage

(determines channel length): $U_{DS_{sat}} = U_{GS} - U_{Th}$

$$I_{DS} = \beta \left(U_{GS} - U_{Th} - \frac{U_{DS_{sat}}}{2} \right) U_{DS_{sat}} = \frac{\beta}{2} (U_{GS} - U_{Th})^2$$

=> I_{DS} independent from U_{DS}

the most common operational mode of MOSFETS

Transconductance: $g_m = \beta (U_{GS} - U_{Th})$
 $= \sqrt{2\beta I_{DS}}$

and: $\frac{g_m}{I_{DS}} = \frac{2}{U_{GS} - U_{Th}}$

FET Operating Principle - NMOS

Summary

Region	weak inversion $U_{GS} < U_{Th}$	linear region $U_{GS} > U_{Th}, U_{DS} < U_{GS} - U_{Th}$	strong inversion $U_{GS} > U_{Th}, U_{DS} \geq U_{GS} - U_{Th}$
I_{DS}	$I_{D0} e^{\frac{U_{GS} - U_{Th}}{n U_T}}$	$\beta \left[U_{GS} - U_{Th} - \frac{U_{DS}}{2} \right] U_{DS}$	$\frac{\beta}{2} (U_{GS} - U_{Th})^2 (1 + \lambda U_{DS})$
g_m	$I_{DS} \frac{q_e}{n k T}$	βU_{DS}	$\sqrt{2 \beta I_{DS}}$

g_m - transconductance

$g_{DS} = 1/R_{DS}$

$$g_m = \frac{dI_{DS}}{dU_{GS}}$$

- In reality: Slight deviation from idealized behavior discussed on the previous slides:

Early Effect also for FETs: Mild dependence of current on U_{DS} in saturation region due to pinch-off, resulting in $g_{DS} \neq 0$. With that:

$$I_{DS} = \frac{\beta}{2} (U_{GS} - U_{Th})^2 (1 + \lambda U_{DS})$$

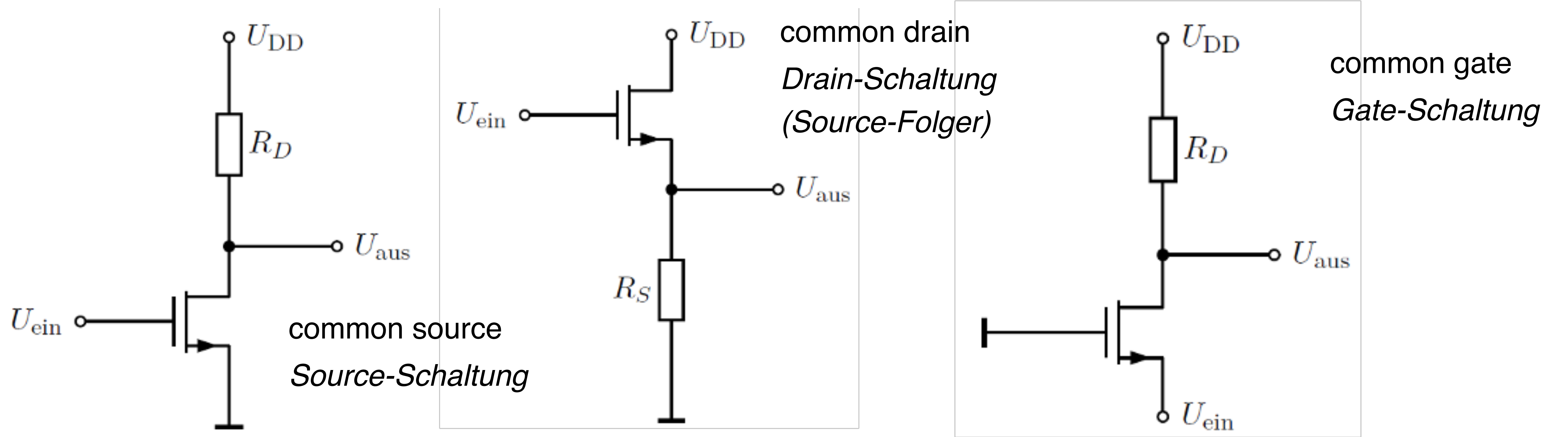
$$\lambda \sim 0.01 - 0.1 \text{ V}^{-1}$$

and:

$$g_{DS} = \frac{dI_{DS}}{dU_{DS}} = \frac{\lambda I_{DS}}{1 + \lambda U_{DS}} \sim \lambda I_{DS}$$

CMOS Circuits

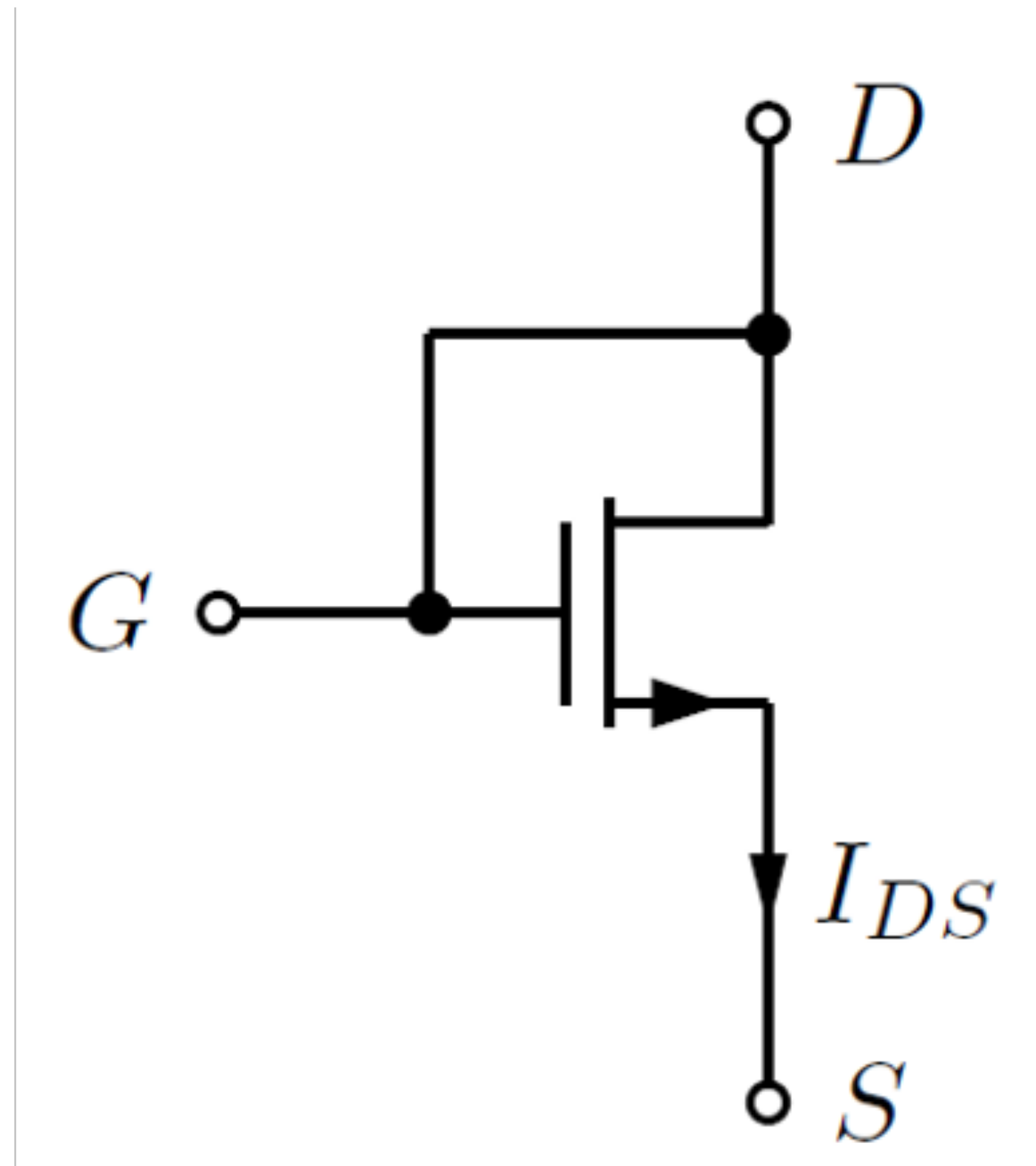
In: Chapter 7: Field Effect Transistors



Eigenschaften	Sourceschaltung	Drainschaltung	Gateschaltung
Eingangsimpedanz	sehr hoch	sehr hoch	klein, $Z_{\text{ein}} \approx \frac{1}{g_m}$
Ausgangsimpedanz	$Z_{\text{aus}} \approx R_D$	„klein“, $Z_{\text{aus}} \approx \frac{1}{g_m} \parallel R_S$	$Z_{\text{aus}} \approx R_D$
Spannungsverstärkung	$V_U = -R_D g_m$	$V_U \approx 1$	$V_U \approx R_D g_m$

FET as a Diode

NMOS configured as a diode



- For positive U_{DS} :

$$U_{DS} = U_{GS} \geq U_{GS} - U_{Th} \quad (\text{as long as } U_{GS} > U_{Th})$$

Operation in saturation region, transistor conductive.

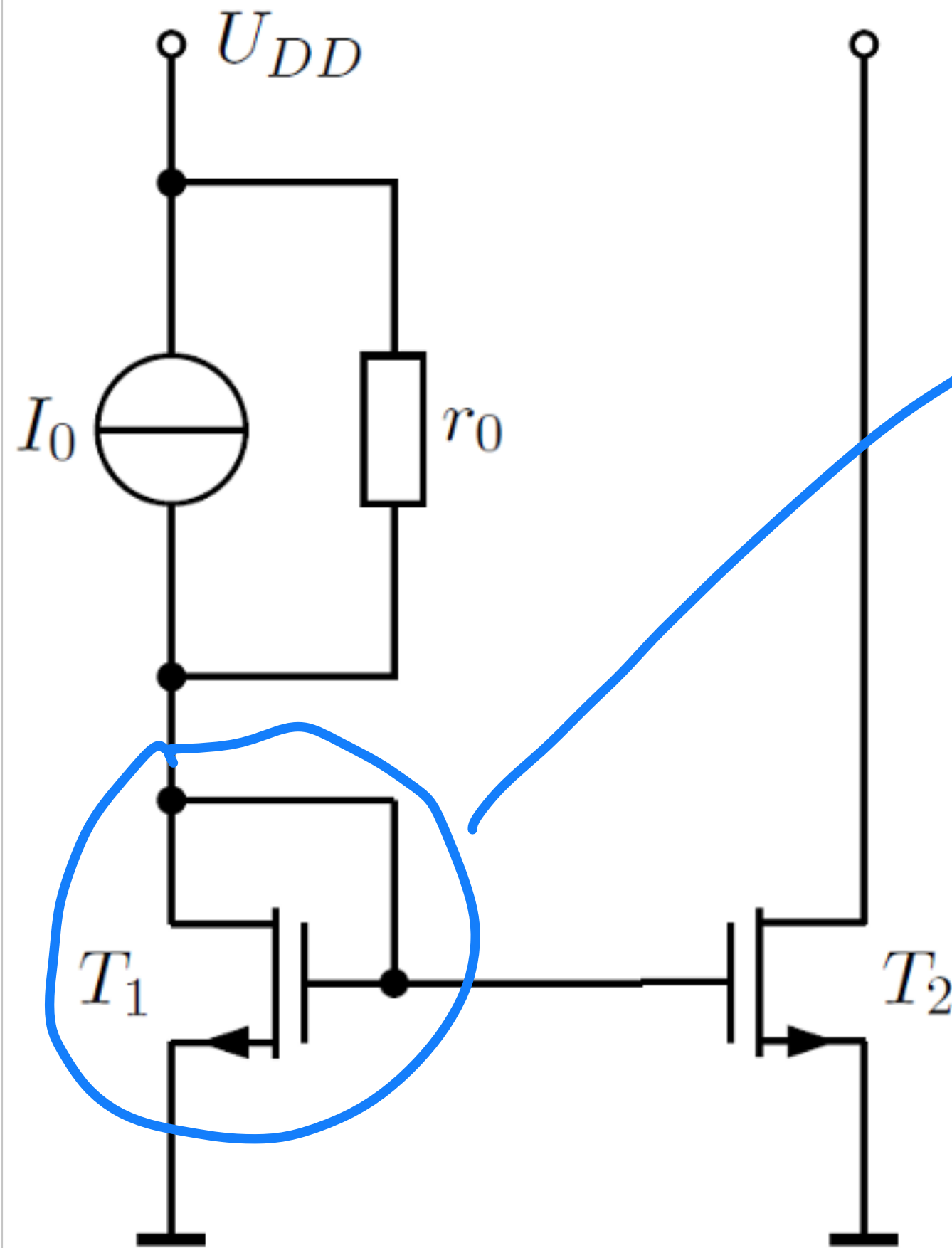
- For negative U_{DS} : transistor in reverse bias

Differential source-drain resistance:

$$r_{DS} = \frac{\partial U_{DS}}{\partial I_{DS}} = \frac{\partial U_{GS}}{\partial I_{DS}} = \frac{1}{g_m}$$

Principle:

reference current through T_1



FET diode: $\Delta U = U_{GS1} = I_1 \cdot r_{DS} = \frac{I_1}{g_{m1}}$

In the saturation region: $g_m = \sqrt{2\beta I_{DS}}$

$\Rightarrow U_{GS1} = \frac{I_1}{\sqrt{2\beta_1 I_1}} = \sqrt{\frac{I_1}{2\beta_1}}$

$\beta = \mu C_{ox} \frac{W}{L}$

$U_{GS1} = U_{GS2}$

$\Rightarrow \frac{I_1}{2\beta_1} = \frac{I_2}{2\beta_2} \Rightarrow \frac{I_1}{I_2} = \frac{\beta_1}{\beta_2} = \frac{W_1 L_2}{W_2 L_1}$

Next Lectures:

Digital - Thursday, January 25

Analog 12 - Chapter 07 - Tuesday, January 30, 2024

Time Plan for Next Lectures

A few Changes coming up!

Calender Week	Tuesday	Thursday
45	07.11. Analog	09.11. Digital
46	14.11. Analog	16.11. Digital
47	21.11. Digital	23.11. Analog
48	28.11. Digital	30.11. Digital
49	05.12. Digital	07.12. Analog
50	12.12. Digital	14.12. Analog
51	19.12. Analog	21.12. Digital
2	09.01. Analog	11.01. Digital
3	16.01. Digital	18.01. Digital
4	23.01. Analog	25.01. Digital
5	30.01. Analog	01.02. Digital
6	06.02. Analog	08.02. Analog
7	13.02. Analog	15.02. Digital

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